

# **General Description:**

The LWS6008A8 uses advanced SGT technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. The package form is TO-220AB, which accords with the ROHS standard and Halogen Free standard.

#### **Features:**

- Fast Switching
- Low Gate Charge and R<sub>DS(ON)</sub>
- Low Reverse transfer capacitances

## **Applications:**

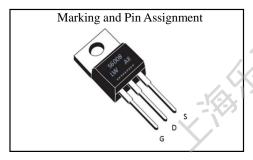
- Battery switching application
- Hard switched and high frequency circuits
- Power Management

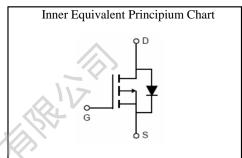
100% DVDS Tested 100% Avalanche Tested





# $V_{DSS}$ -60 V $I_{D}$ -110 A $P_{D}$ 180 W $R_{DS(ON) TYPE}$ 5.5 mΩ





# Package Marking and Ordering Information:

Marking	Part Number	Package	Packing	Qty.
S6008/LW A8/D.C.	LWS6008A8	TO-220AB	Tube	50 Pcs

## **Absolute Maximum Ratings:**

Symbol	Parameter		Value	Units
V <sub>DSS</sub>	Drain-to-Source Voltage		-60	V
т	Continuous Drain Current	$T_{C}=25^{\circ}C$	-110	A
$I_{D}$	Continuous Drain Current	$T_C=100^{\circ}C$	-70	A
${ m I_{DM}}^{ m a1}$	Pulsed Drain Current		-440	A
$V_{GS}$	Gate-to-Source Voltage		±20	V
$P_{D}$	Power Dissipation		180	W
$E_{AS}^{a2}$	Single pulse avalanche energy		960	mJ
$T_{J}, T_{STG}$	Operating Junction and Storage Temp	perature Range	150, -55 to 150	$^{\circ}\mathbb{C}$
TL	Maximum Temperature for Solderi	ng	260	C

## **Thermal Characteristics:**

Symbol	Parameter	Value	Units
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	0.69	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient	-60	°C/W



# **Electrical Characteristic** ( $T_A = 25$ °C, unless otherwise specified):

Static Ch	naracteristics					
Cramb of	Domomoton	Tost Conditions		Value		TT '.
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$V_{\rm DSS}$	Drain to Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250 \mu A$	-60			V
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS} = -60V, V_{GS} = 0V$			1.0	μΑ
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}$ =-20V, $V_{DS}$ =0V			100	nA
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS} = +20V, V_{DS} = 0V$			-100	nA
$V_{\text{GS(TH)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-1.6	-2.0	-2.4	V
R <sub>DS(ON)</sub>	Drain-to-Source On-Resistance	$V_{GS}$ =-10V, $I_{D}$ =-15A		5.5	7.0	mΩ

Dynamic Characteristics								
Symbol	Parameter	Test Conditions	Value			Units		
Symbol	rarameter	Test Conditions	Min.	Typ.	Max.	Ullits		
C <sub>iss</sub>	Input Capacitance	$V_{GS} = 0V$	1	5403				
$C_{oss}$	Output Capacitance	$V_{DS} = -30V$	7	941		pF		
$C_{rss}$	Reverse Transfer Capacitance	f = 1.0MHz	186	48				
$R_{G}$	Gate resistance	V <sub>GS</sub> =0V,V <sub>DS</sub> Open	()) <del>-</del>	2.0		Ω		

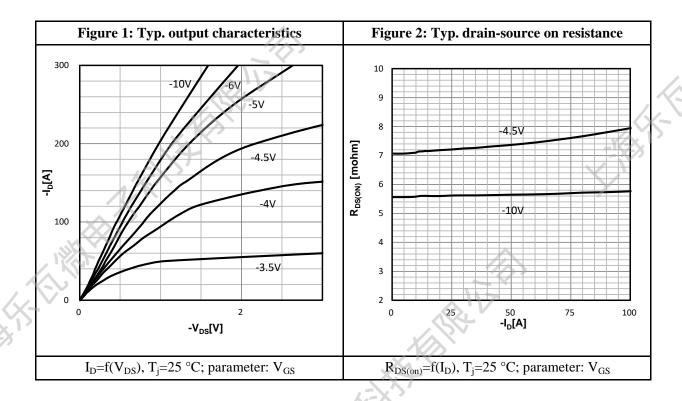
Resistive Switching Characteristics							
Symbol	Parameter	Test Conditions	Value			Units	
Symbol	Farameter	Test Collections	Min.	Тур.	Max.	Omts	
$t_{d(ON)}$	Turn-on Delay Time	$I_{D} = -15A$		4.5			
t <sub>r</sub>	Rise Time	$I_D = -15A$ $V_{DS} = -30V$		2.5		200	
$t_{d(OFF)}$	Turn-Off Delay Time	$V_{GS} = -10V$		14.5		ns	
$t_{\rm f}$	Fall Time	$R_G = 3\Omega$		3.5			
$Q_{\mathrm{g}}$	Total Gate Charge	$V_{GS} = -10V$		80			
$Q_{gs}$	Gate Source Charge	$V_{DS} = -30V$		15		nC	
$Q_{\mathrm{gd}}$	Gate Drain Charge	$I_D = -15A$		11			

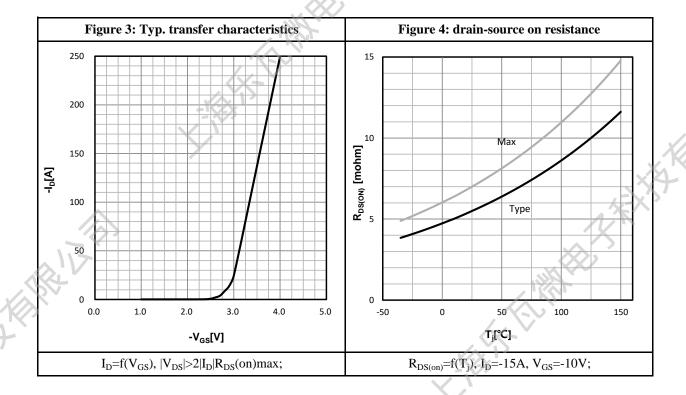
Source-Dr	Source-Drain Diode Characteristics							
Symbol	Parameter	Test Conditions	Value		Units			
Symbol	r ai ailictei	Test Collutions	Min.	Typ.	Max.	Omts		
$I_{S}$	Diode Forward Current	$T_C = 25  ^{\circ}C$			-110	A		
$V_{SD}$	Diode Forward Voltage	$I_S$ =-15A, $V_{GS}$ =0V			-1.2	V		
t <sub>rr</sub>	Reverse Recovery time	$I_{S}$ =-15A, $V_{DD}$ =-30V,		60		ns		
$Q_{rr}$	Reverse Recovery Charge	dI/dt=100A/us		105	1	nC		

a1: Repetitive rating; pulse width limited by maximum junction temperature a2:  $V_{DD}$ =-30V,L=1.0mH,  $R_G$ =25 $\Omega$ , Starting  $T_j$ =25 $^{\circ}$ C

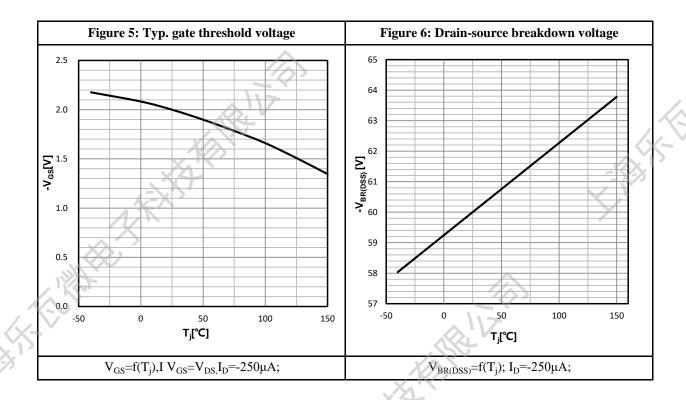


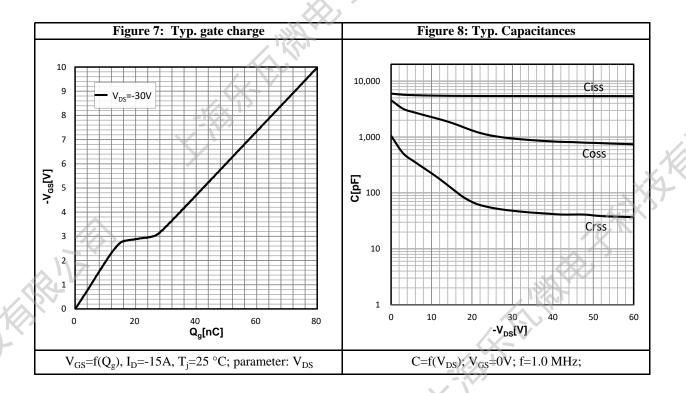
## **Characteristics Curve:**



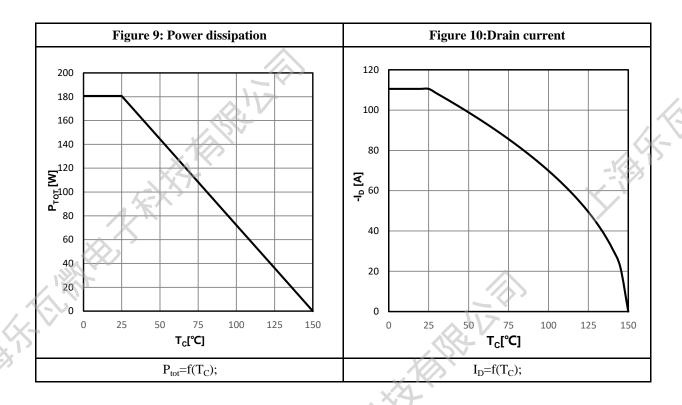


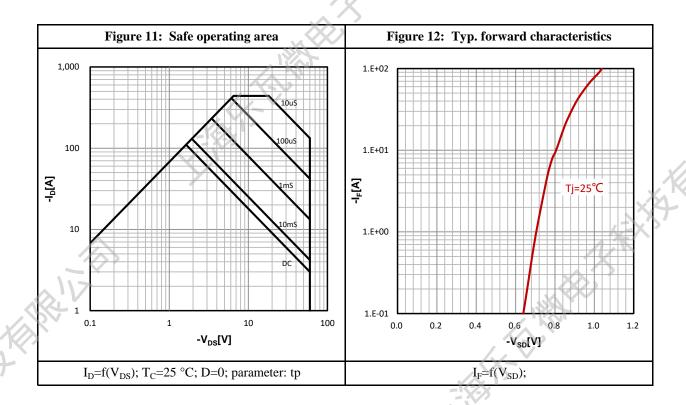




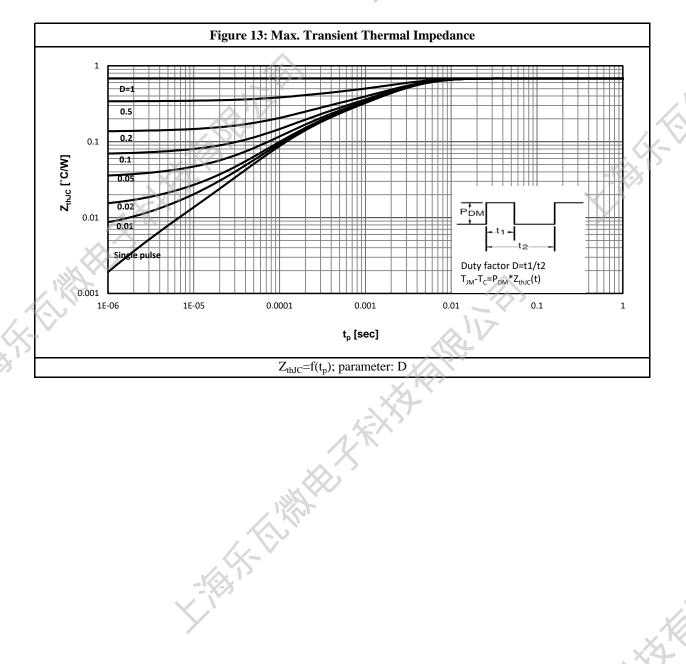














## **Test Circuit & Waveform:**

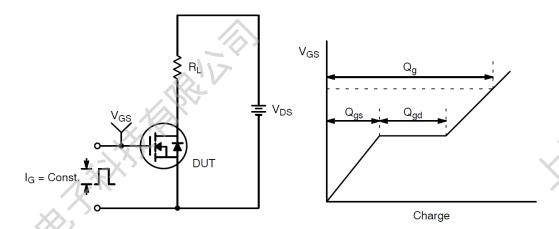


Figure 14: Gate Charge Test Circuit & Waveform

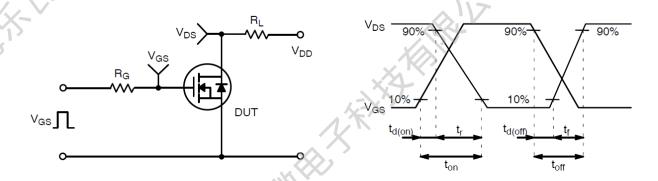


Figure 15: Resistive Switching Test Circuit & Waveforms

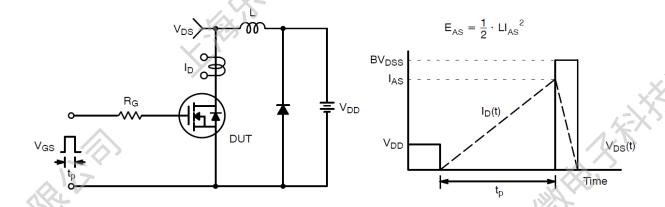
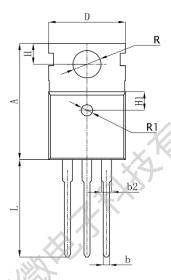
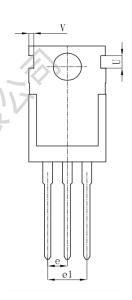


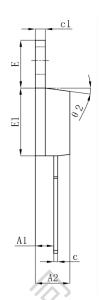
Figure 16: Unclamped Inductive Switching Test Circuit & Waveforms

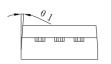


## **Package Outline:**









SYMBOL	-1.7	MILLIMETER	
STIVIDOL	MIN	NOM	MAX
А	15.4	15.6	15.8
A1	2.3	2.4	2.5
A2	4.4	4.5	4.7
b	0.7	0.8	0.9
b2	1.18	1.31	1.44
С	0.44	0.5	0.56
c1	1.28	1.3	1.32
D	9.8	10	12.2
E	6.4	6.5	6.6
E1	9	9.1	9.2
е	2.42	2.54	2.66
e1	4.84	5.08	5.32
Н	2.73	2.8	2.87
H1	2.4	2.5	2.6
L	13.02	13.37	13.72
R	3.5	3.6	3.63
R1	1.4	1.5	1.6
U	1.65	1.75	1.85
V	0.58	0.68	0.78
q 1	2°	2.5°	3°
q 2	6.5°	7°	7.5°

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## **Revision History:**

Γ	Revison	Date		Descriptions	
	Rev 1.0	Mar.2022	Initial Version		
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#### **Disclaimer:**

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